2015 31st Thermal Measurement, Modeling & Management Symposium

(SEMI-THERM 2015)

San Jose, California, USA
15-19 March 2015

IEEE Catalog Number: CFP15SEM-POD
ISBN: 978-1-4799-8596-8

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SUBMIT A PAPER FOR SEMI-THERM 32!

As you further develop a technique or application, consider documenting it for the thermal community. **SEMI-THERM 32** will begin accepting abstracts during the summer (deadline is September 15, 2015). We welcome your submissions! Visit us at **www.semi-therm.org**.